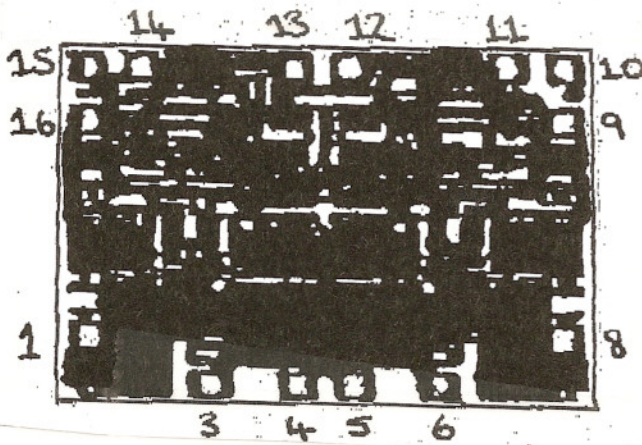




Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>Pad</u>	<u>Function</u>	<u>Pad</u>	<u>Function</u>
1	D ₁	9	S ₂
2	NC	10	IN ₂
3	D ₃	11	V ⁺
4	S ₃	12	V _L
5	S ₄	13	GND
6	D ₄	14	V ⁻
7	NC	15	IN ₁
8	D ₂	16	S ₁

NOTE: NC = No Connect

Topside Metal: -
Backside: -
Backside Potential: -
Mask Ref: -
Bond Pads : .004"

APPROVED BY: CD
MFG: Harris

DIE SIZE : .085" x .068"
THICKNESS: -

DATE: 6/28/02
P/N: DG403